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TITLE: PLASMA PROCESSES FOR DEPOSITING LOW DIELECTRIC
CONSTANT FILMS
INVENTOR: DAVID CHEUNG, ET AL.
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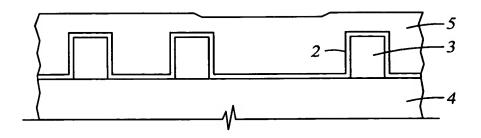


Fig. 1A (PRIOR ART)

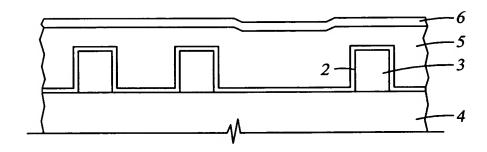
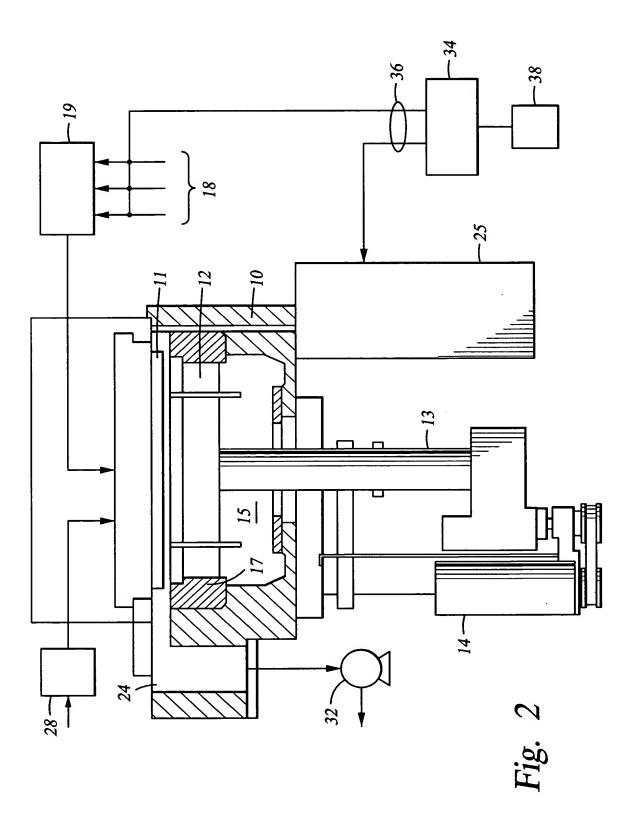


Fig. 1B (PRIOR ART)

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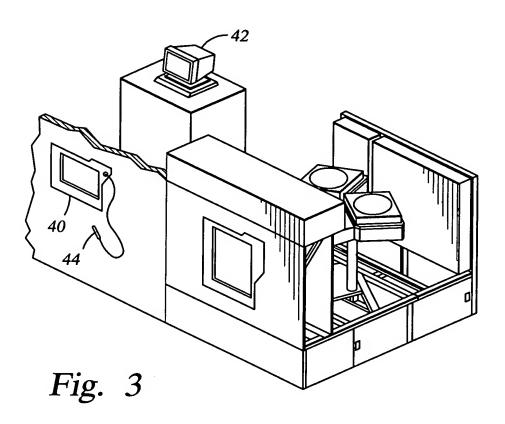
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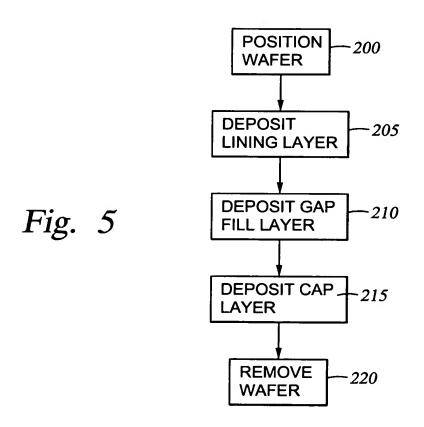
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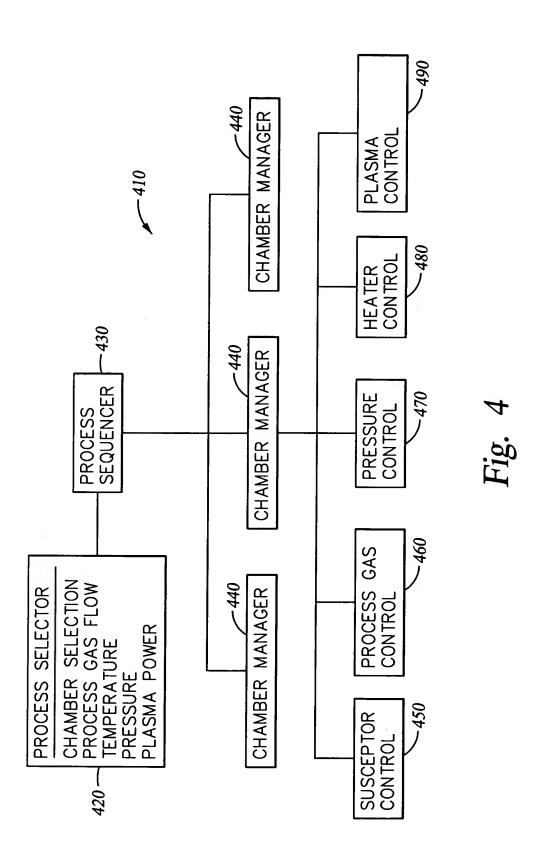




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TITLE: PLASMA PROCESSES FOR DEPOSITING LOW DIELECTRIC
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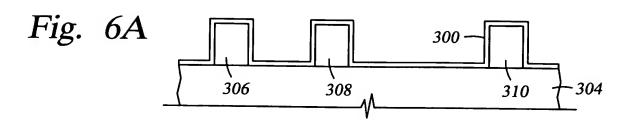
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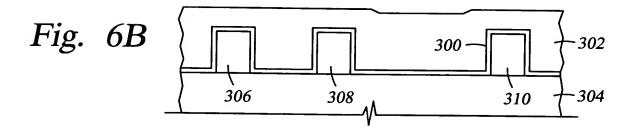
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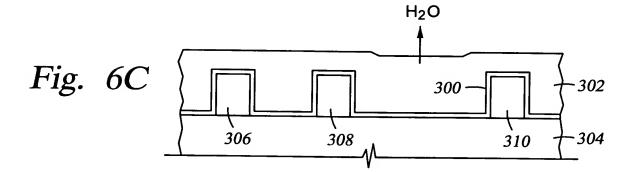
CONSTANT FILMS DAVID CHEUNG, ET AL.

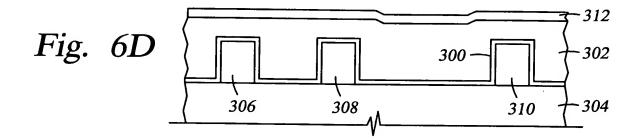
INVENTOR: PAGE 5 OF 10 EXPRESS MAIL NO.: EV335470127US

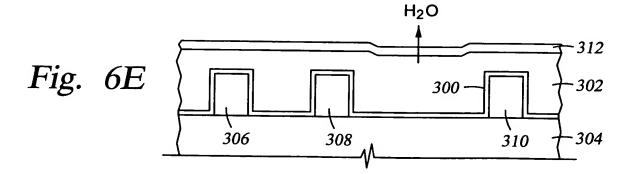
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PLASMA PROCESSES FOR DEPOSITING LOW DIELECTRIC APPLICANT: TITLE: CONSTANT FILMS
INVENTOR: DAVID CHEUNG, ET AL.
EXPRESS MAIL NO.:EV335470127US PAGE 6 OF 10 6/10 520 516 -518 -514 Fig. 7 -510 -512 -510 Fig. 8A 512 514 Fig. 8B -510 512 516 516 -514 Fig. 8C -510 512 -518 516 516 Fig. 8D 514 -510 -512 L

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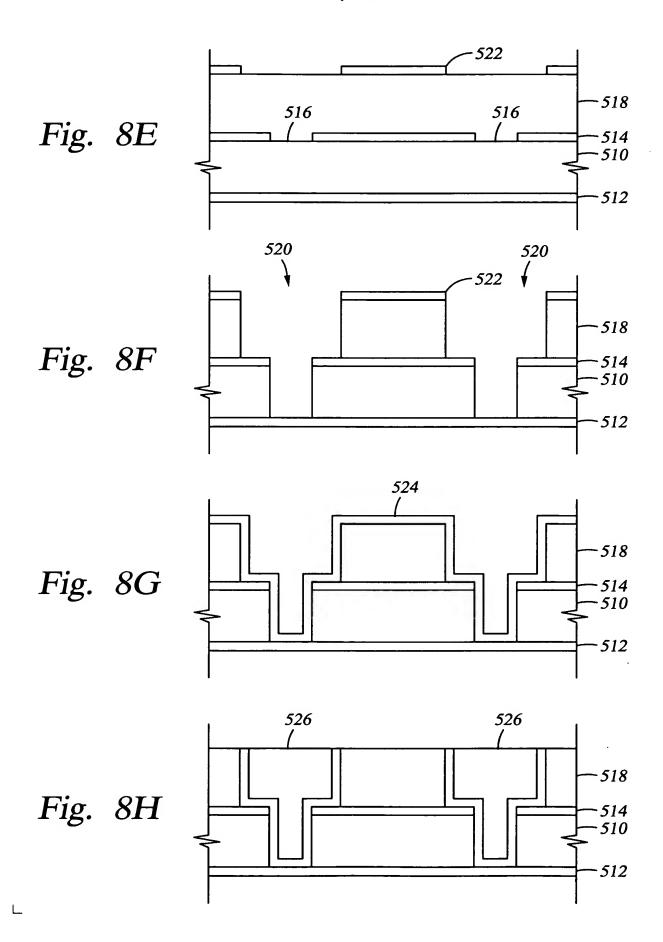
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CONSTANT FILMS
INVENTOR: DAVID CHEUNG, ET AL.
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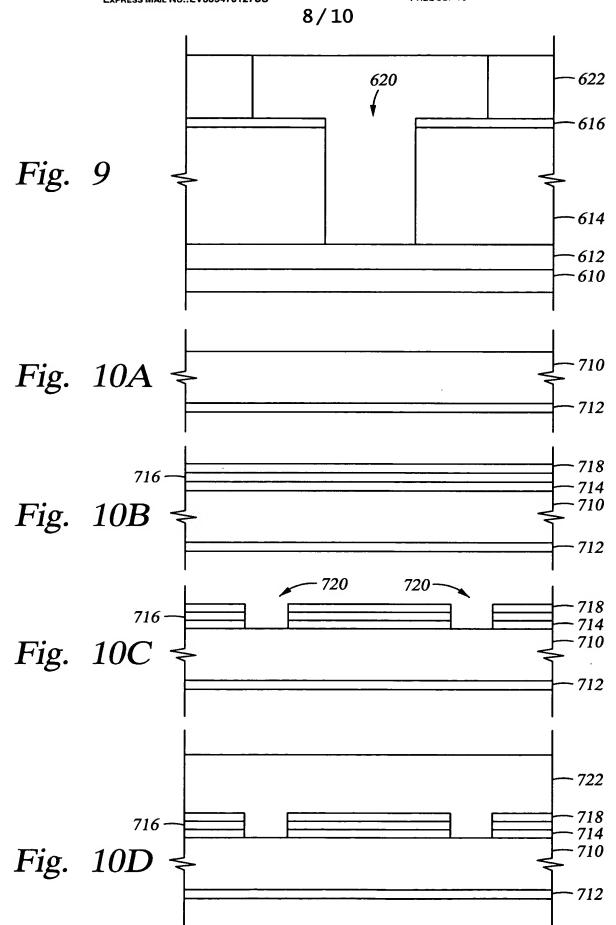
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PLASMA PROCESSES FOR DEPOSITING LOW DIELECTRIC TITLE:

CONSTANT FILMS
INVENTOR: DAVID CHEUNG, ET AL.
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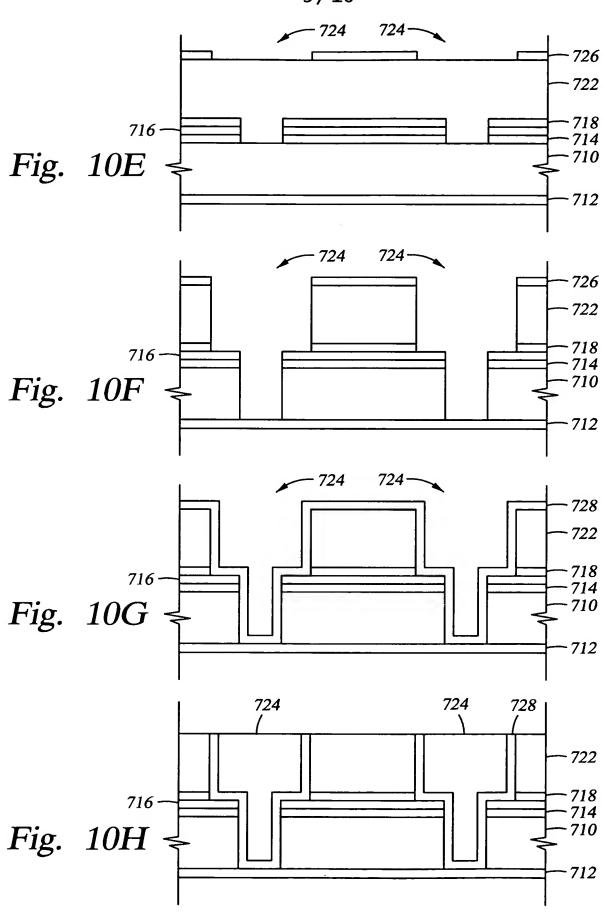
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